

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	49	("4178188" "4401131" "4501285" "4543130" "4633893" "4778532" "4804007" "4856544" "4899767" "4911761" "4917123" "4979994" "4984597" "4998549" "5037208" "5037481" "5148823" "5203798" "5247954" "5279316" "5286657" "5333628" "5339842" "5365960").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/31 13:29
L2	19	("4082565" "4475259" "4652106" "4728368" "4806277" "4854337" "4902350" "5017236" "5038808" "5090430").PN. OR ("5203798").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2005/10/31 14:00
L3	1	"6799588".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2005/10/31 14:01
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L5	1	"6799588"	DERWENT	ADJ	ON	2005/10/31 14:10

DERWENT-ACC-NO: 2002-061687

DERWENT-WEEK: 200465

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TITLE: Substrate treatment device has each substrate
fed through treatment fluid in process container
provided with variable overflow opening

INVENTOR: MEURIS, M; SCHNEIDER, J ; SPEH, U

PATENT-ASSIGNEE: STEAG MICROTECH GMBH[STGG] , IMEC[IMECN],
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MATTSON WET PROD GMBH[MATTN], IMEC VZW[IMECN]

PRIORITY-DATA: 1999DE-1034300 (July 21, 1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES MAIN-IPC		
US <u>6799588</u> B1	October 5, 2004	N/A
000 B08B 003/04		
WO 200108200 A1	February 1, 2001	G
021 H01L 021/00		
DE 19934300 A1	April 5, 2001	N/A
000 H01L 021/306		
DE 19934300 C2	February 7, 2002	N/A
000 H01L 021/306		
EP 1208586 A1	May 29, 2002	G
000 H01L 021/00		
KR 2002063157 A	August 1, 2002	N/A
000 H01L 021/00		
TW 487960 A	May 21, 2002	N/A
000 H01L 021/02		
JP 2003505881 W	February 12, 2003	N/A
022 H01L 021/304		

DESIGNATED-STATES: JP KR SG US AT BE CH CY DE DK ES FI FR GB GR IE IT
LU MC NL
PT SE AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
US 6799588B1	N/A	2000WO-EP06716

July 14, 2000		
US 6799588B1	N/A	2002US-0031923
April 17, 2002		
US 6799588B1	Based on	WO 200108200
N/A		
WO 200108200A1	N/A	2000WO-EP06716
July 14, 2000		
DE 19934300A1	N/A	1999DE-1034300
July 21, 1999		
DE 19934300C2	N/A	1999DE-1034300
July 21, 1999		
EP 1208586A1	N/A	2000EP-0954498
July 14, 2000		
EP 1208586A1	N/A	2000WO-EP06716
July 14, 2000		
EP 1208586A1	Based on	WO 200108200
N/A		
KR2002063157A	N/A	2002KR-0700862
January 21, 2002		
TW 487960A	N/A	2000TW-0114474
August 31, 2000		
JP2003505881W	N/A	2000WO-EP06716
July 14, 2000		
JP2003505881W	N/A	2001JP-0512620
July 14, 2000		
JP2003505881W	Based on	WO 200108200
N/A		

INT-CL (IPC): B08B003/04, B08B003/12 , H01L021/00 , H01L021/02 ,
H01L021/304 , H01L021/306

ABSTRACTED-PUB-NO: WO 200108200A

BASIC-ABSTRACT:

NOVELTY - The substrate treatment device has a process container (8) within a gas atmosphere, holding a treatment fluid (20) through which each substrate (3) is passed, between aligned entry and outlet openings (15,16) of the container, positioned below the surface of the treatment fluid, maintained at a given height via a variable overflow opening (17) leading to an overflow container (42).

USE - The device is used for treating the surface of a substrate, e.g. a

semiconductor wafer.

ADVANTAGE - The overflow allows the treatment fluid within the process container to be maintained at a given level.

DESCRIPTION OF DRAWING(S) - The figure shows a schematic cross-section through a substrate treatment device.

Substrate 3

Process container 8

Entry and outlet openings of process container 15,16

Overflow opening 17

Treatment fluid 20

Overflow container 42

CHOSEN-DRAWING: Dwg.1/2

TITLE-TERMS: SUBSTRATE TREAT DEVICE SUBSTRATE FEED THROUGH TREAT FLUID PROCESS

CONTAINER VARIABLE OVERFLOW OPEN

DERWENT-CLASS: P43 U11

EPI-CODES: U11-C09X;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2002-045794